

## Sintering 1995 Issues Call for Papers

Papers are being solicited for Sintering 1995, an International Conference on the Science, Technology and Applications of Sintering. The conference will be held September 24-27, 1995 at the Penn State Scanticon Conference Center Hotel, University Park, Pennsylvania. The program is chaired by Randall M. German and Gary L. Messing, both professors at Penn State, and coordinated by an international organizing committee of 29 recognized experts in the field.

Sintering 1995 will explore both the science and applications of sintering processes for materials fabrication. New modeling and simulations of bonding and densification processes will be investigated, as will novel and alternative processes to conventional sintering. A special session will focus on future needs and directions in this field.

The program will include invited lectures and contributed papers and poster presentations by the international sintering community. Suppliers will participate in a table-top exhibition.

Materials to be covered include the following: ceramics, metals, composites/cermets, nanocrystalline materials, optical ceramics, non-oxides, electronic ceramics, high-speed steels, cemented carbides, refractory materials (W, Mo, Ta, Nb), intermetallics, and amorphous materials.

Program topics are as follows:

- Modeling and simulation of sintering,
- Modeling of grain growth,
- Computer simulations,
- Sintering kinetics,
- Liquid-phase sintering,
- Processing-sintering-microstructure relationships,
- In situ* microscopy of sintering,
- Dimensional control,
- Sintering reactive systems,
- Novel sintering techniques,
- Pressure-assisted densification,
- Atmospheric effects and control, and
- Microstructure characterization.

Sintering 1995 is endorsed by the American Ceramic Society, APMI International, International Institute for the Science of Sintering, Metal Powder Industries Federation, and the Materials Research Society.

The call for papers deadline is **November 15, 1994**. For more information, contact: Particulate Materials Center, Pennsylvania State University, 147 Research Building West, University Park, PA 16802-6809. Phone: (814) 863-6156; fax: (814) 863-9704; e-mail: rgc5@oas.psu.edu.

## Beijing Conference to Focus on Solid-State and IC Technology

The Fourth International Conference on Solid-State and Integrated Circuit technology will be held October 24-28, 1995, in Beijing, China. The Chinese Institute of Electronics is sponsoring the conference in cooperation with the IEEE Solid-State Circuits Council, Japan Society of Applied Physics, IEE Electronics Division (United Kingdom), and the IEE Beijing Section of the Korea Institute of Telematics and Electronics. The conference is supported by the National Natural Science Foundation of China and is endorsed by the Materials Research Society.

ICSICT '95 will offer a broad review of materials and processing issues associated with fabricating IC and solid-state devices. Talks, panel discussions, and technical tours will be featured.

Papers are solicited in, but not limited to, the following topics:

- Silicon ULSI technology, materials, and processing,
- SOI technology and devices,
- Device physics and performance,
- Circuit design,
- Reliability and failure mechanisms of submicron structures,
- Packaging technology, materials, and processing,
- Computer-aided design and testing,
- Compound semiconductors, materials, and processing,
- Optoelectronic materials and devices,
- Dielectric materials and ultrathin gates,
- Selective deposition and planarization,
- Ion implantation and doping,
- Multilayer interconnections and vias,
- Silicides, thin-film reactions, and interfaces,
- Characterization and analysis techniques,
- Amorphous and polycrystalline silicon technology,

Flat panel display technology, and Emerging technologies and environmental issues.

Abstracts (300 words, in English, on 8 1/2 by 11 inch paper with 1 1/2 inch margins) are due at the addresses listed no later than **December 1, 1994**. Include authors names, affiliations, mailing addresses, and telephone and fax numbers. Submit an original and three copies as follows:

- Authors in PRC: Prof. Jisheng Zhang, Institute of Microelectronics, Tsinghua University, Beijing, China. Phone: (1) 259 5499; fax (1) 256-1250.

- Authors elsewhere in Asia: Prof. Masataka Hirose, Research Center for Integrated Systems, Hiroshima University, Higashi-Hiroshima 724, Japan. Phone: (0824) 24-7655; fax (0824) 22-7038.

- Authors in Europe: Prof.-Dr. Hans J. Queisser, Max-Planck-Institut, Heisenbergstrasse 1, D-70569 Stuttgart, Germany. Phone: (711) 689-1600; fax (711) 689-1602.

- Authors in North and South America: Dr. Gary L. Baldwin, Hewlett-Packard Labs., P.O. Box 10350, M/S 26MR9, Palo Alto, CA 94303-0867, USA. Phone: (415) 857-4143; fax (415) 857-2379; e-mail: baldwin@hpl.hp.com.

For further information, please contact either of the following: Ms. Ziaonan Zhang, ICSICT '95 Secretariat, P.O. Box 165, Beijing 100036, China; phone: (1) 826-3459; fax: (1) 826-3458; e-mail: shaz%bepec2@scs.slac.stanford.edu. Dr. C.C. Tsai, Xerox Palo Alto Research Center, 3333 Coyote Hill Road, Palo Alto, CA 94304, USA; Tel: (415) 812-4515; fax (415) 493-6349; e-mail: tsai.parc@xerox.com. □

### Advanced Materials and Marine Applications Technical Symposium & Workshop on Russian Technology September 20 - 22, 1994 • Pennsylvania State University

The culmination of over two years of technical discussions and visits, this event highlights promising materials developments from PROMETEX Central Research Institute of Structural Materials, the largest materials science organization in Russia, and KRYLOV Shipbuilding Research Institute, representing the center of the Russian shipbuilding industry.

**Topics:** High-strength steels and welding, titanium and welding, composite materials and coatings, amorphous materials, materials quality evaluation methods, and new materials in marine acoustics. Also: Funding sources and strategy roundtables, product displays, and technical abstracts

**Information:** Ed Pope (phone 814-865-2921) or Leanne Zindler (phone 814-863-4344) at Pennsylvania State University, Applied Research Laboratory, P.O. Box 30, State College, PA 16804; fax (814) 863-0673.

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